



Downloaded from Arrow.com.

		2	3		4	5		6	
	TOP LAYER			PLAT	TABLE I (HCI P ED THROUGH-HOLE				
	DESCRIPTION	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	TIN THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER
	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015					0.65 - 0.80
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050				0.9 - I.5um		0.70 - 0.80
	IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050					0.15 - 0.65um	0.70 - 0.80
C 0	PPER (SEE NOTE 9)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050						0.70 - 0.80
	GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050		0.003 - 0.007	FLASH UP TO 0.0002			0.69 - 0.80
		0.01 0.00 (0.03 DRTEE)	0.020 0.000		0.005 0.001	FLASH OF TO 0.000Z			0.00 0.00
	TOP LAYER				TABLE 2 (HPC SI ED THROUGH-HOLE	GNALS)			
		DRILLED HOLE DIAMETER	COPPER THICKNESS		TABLE 2 (HPC SI	GNALS)	T I N THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETE
	TOP LAYER	DRILLED HOLE	COPPER	PLAT TIN-LEAD	TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL	IGNALS) REQUIREMENTS GOLD	T I N	SILVER	FINISHED
	TOP LAYER DESCRIPTION	DRILLED HOLE DIAMETER I.125-I.175	COPPER THICKNESS	PLAT TIN-LEAD THICKNESS	TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS	GNALS) REQUIREMENTS GOLD THICKNESS	T I N T H I C K N E S S	SILVER THICKNESS	FINISHED HOLE DIAMETE 0.94 - I.I0
	TOP LAYER DESCRIPTION TIN-LEAD	DRILLED HOLE DIAMETER I.125-I.175	COPPER THICKNESS	PLAT TIN-LEAD THICKNESS 0.005 - 0.015	TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS 	GNALS) REQUIREMENTS GOLD THICKNESS 	T I N T H I C K N E S S	SILVER THICKNESS 	FINISHED HOLE DIAMETE 0.94 - I.I0
	TOP LAYER DESCRIPTION TIN-LEAD IMMERSION TIN	DRILLED HOLE DIAMETER I.125-I.175	COPPER THICKNESS	PLAT TIN-LEAD THICKNESS 0.005 - 0.015 	TABLE 2 (HPC SI ED THROUGH-HOLE NICKEL THICKNESS 	IGNALS) REQUIREMENTS GOLD THICKNESS 	TIN THICKNESS 	SILVER THICKNESS 	FINISHED HOLE DIAMETE 0.94 - I.I0

D

Copyright FCI.

F

E

Pre/E File - REV C - 2009-06-09 Downloaded from Arrow.com. 8

В

С

D

F

dr	NotFound DuWa	20	10/04/27	proje	ection	N	1 M	size	S	cale	
eng	De-Ming Lu	20	14/12/27			١v	v	A 2		1:1	
chr	-	-		$\mathbb{A}$		-		ecn no	E	ELX-DG-1984	9-1
appr	Pei-Ming Zheng	20	14/12/29	product	family		-	rel level		Releas	sed
F	<b>Čj</b> <u>°</u> R / A		₩ R/A REPT ASSY IODC-24S		S	dwg no	100658	66	r	rev F	
www.	fci.com	t. no.	1	-	Pro	oduct –	Customer	Drw	sheet	3 of 4	
S: Rev :F			ST	ATUS:F	Released		Pri	inted: Dec	30, 20	014	

			2		3	4	5	6	7	8	
	PART NUMBER	RETENTION CLIPS	#4 SCREW	DIM A (TAIL LEN							
	10065866-001LF	NO	YES	3.43	SOLDER TAIL						
	10065866-002LF	NO	YES	4.70	SOLDER TAIL						
A	10065866-003LF	YES	NO	3.43	SOLDER TAIL			<u>^</u>			Δ
	10065866-004LF	YES	NO	4.70	SOLDER TAIL						A

$\sim$	

NOTES:

В

С

D

F

**S** 

Copyright FCI.

F

Downloaded from Arrow.com.

Pro/E File - REV C - 2009-06-09

- I. CONNECTOR MATERIALS: HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK UL 94V-0 COMPLIANT CONTACTS: HIGH PERFORMANCE COPPER ALLOY
- 2. CONTACT FINISH (REF. GS-12-380 SECTION 5.2)
- 3. PRODUCT SPECIFICATION: GS-12-380.
- 4. APPLICATION SPECIFICATION: GS-20-070.
- (5.) PRODUCT MARKING (PRODUCT NUMBER & DATE CODE) ON HOUSING IN AREA SHOWN.
- (6.) MINIMUM NOMINAL PCB THICKNESS: I.6mm
- 7. PACKAGING MEETS FCI SPECIFICATION GS-14-1073.
- (8.) HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
- (9.) COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
- IO. ALL HOLE SIZES ARE FINISHED HOLE SIZES.
- (II.) MOUNTING HOLES ARE UNPLATED.

3

DS: Rev :F STATUS					:Released			Printed: Dec 30, 2014			
www.	fci.com cat. no.			- Product -			– Customer Drw		sheet 4 of 4		
F	CÌ	– R/. + + HCI	A REPT AS		)DC - 24	S	dwg no	100658	66	rev F	
appr	Pei-Ming Zheng		014/12/29 product f		family		-	rel level	Re	ELX-DG-19849-1 Released	
chr	-		-	$\oplus$ $\Box$		→		ecn no	ELX-D		
e n g	eng De-Ming Lu		2014/12/27				MM		3:	3:1	
dr	NotFound DuWa 20		010/04/27 proj		ection	N	1 N /	size A 2	sca	e	

 $\bigcirc$ 

 $\bigcirc$ 

 $\bigcirc$ 

В

D